

BAS19 THRU BAS21

Features

- Ideally Suited for Automatic Insertion
- 150°C Junction Temperature
- Fast Switching speed
- Epitaxial Planar Die Construction

Mechanical Data

- Case: SOT-23, Molded Plastic
- Weight: 0.008 grams (approx.)
- Marking Code

Part Number	Marking	Continuous Reverse Voltage V_R (V)	Repetitive Peak Reverse Voltage V_{RRM} (V)
BAS19	JP	100	120
BAS20	JR	150	200
BAS21	JS	200	250

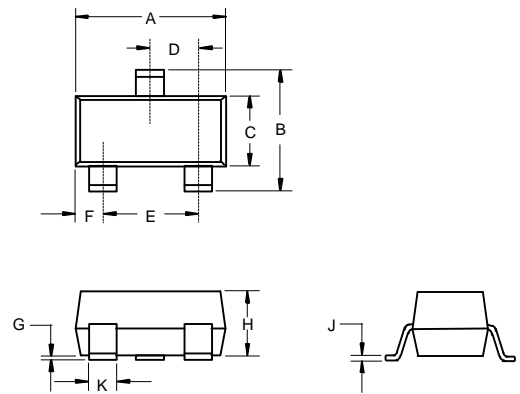
Maximum Ratings @ 25°C Unless Otherwise Specified

Parameter	Symbol	Value	Unit
Non-repetitive Peak Reverse Voltage @ $t=1\mu s$	I_{FSM}	2.5	A
Average Rectified Forward Current	$I_{F(AV)}$	200 ⁽¹⁾	mA
Forward DC Current at $T_{amb}=25^\circ C$	I_F	200 ⁽²⁾	mA
Repetitive Peak Forward Current	I_{FRM}	625	mA
Power Dissipation up to $T_{amb}=25^\circ C$	P_{tot}	250	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	430	°C/W
Operating & Storage Temperature	T_j, T_{STG}	-65~150	°C

- Notes:** (1) Measured under pulse conditions;
Pulse time = $t_p \leq 0.3ms$
(2) Device on fiberglass substrate,
See layout on next page

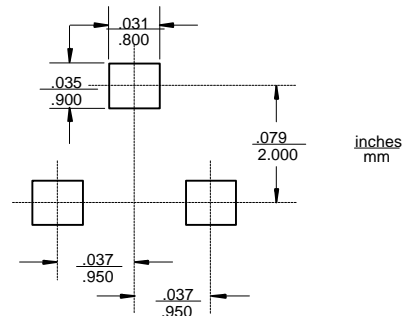
Small Signal Diodes 250mW

SOT-23



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.110	.120	2.80	3.04	
B	.083	.098	2.10	2.64	
C	.047	.055	1.20	1.40	
D	.035	.041	.89	1.03	
E	.070	.081	1.78	2.05	
F	.018	.024	.45	.60	
G	.0005	.0039	.013	.100	
H	.035	.044	.89	1.12	
J	.003	.007	.085	.180	
K	.015	.020	.37	.51	

Suggested Solder Pad Layout



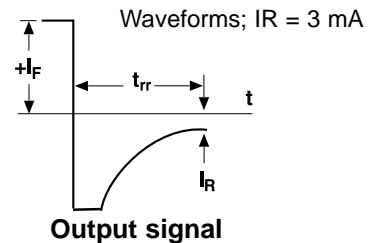
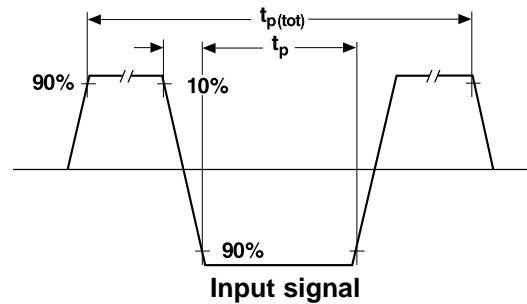
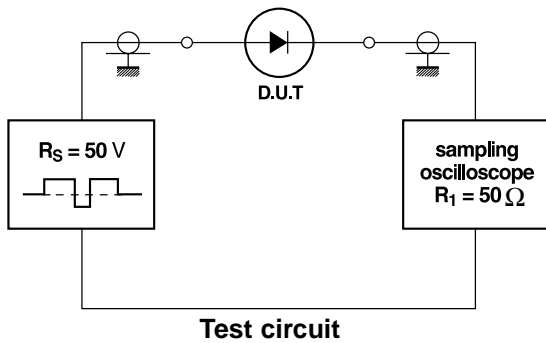
BAS19 thru BAS21

Electrical Characteristics (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V _F	I _F = 100mA	—	—	1.0	V
		I _F = 200mA	—	—	1.25	V
Leakage Current	I _R	V _R = V _{Rmax}	—	—	100	nA
		V _R = V _{Rmax} ; T _J = 150°C	—	—	100	μA
Dynamic Forward Resistance	r _f	I _F = 10mA	—	5	—	Ω
Capacitance	C _{tot}	V _R = 0 f = 1MHz	—	—	5	pF
Reverse Recovery Time (see figures)	t _{rr}	I _F = 30mA, I _R = 30mA I _{rr} = 3mA, R _L = 100Ω	—	—	50	ns

(1) Device on fiberglass substrate, see layout (SOT-23).

Test Circuit and Waveforms (BAS19, BAS20, BAS21)



Input Signal	- total pulse duration - duty factor - rise time of reverse pulse - reverse pulse duration	tp(tot) = 2μs δ = 0.0025 tr = 0.6ns tp = 100ns
Oscilloscope	- rise time - circuit capacitance*	tr = 0.35ns C < 1pF

*C = oscilloscope input capacitance + parasitic capacitance

Layout for R_{ΘJA} test

Thickness: Fiberglass 0.059 in. (1.5 mm)
Copper leads 0.012 in. (0.3 mm)

